



Material Content Data Sheet



Sales Product Name		IPS65R1K0CE		Issued		1. August 2018		
MA#		MA001279160						
Package		PG-TO251-3-342		Weight*		318.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.509	0.79	0.79	7881	7881
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	iron	7439-89-6	0.147	0.05		463	
	non noble metal	copper	7440-50-8	147.096	46.21	46.27	461995	462597
	non noble metal	aluminium	7429-90-5	0.488	0.15	0.15	1532	1532
wire	non noble metal	aluminium	7429-90-5	0.488	0.15	0.15	1532	1532
encapsulation	organic material	carbon black	1333-86-4	1.412	0.44		4435	
	plastics	epoxy resin	-	24.709	7.76		77607	
	inorganic material	silicondioxide	60676-86-0	115.076	36.14	44.34	361426	443468
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11747	11747
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4461	4472
solder	non noble metal	tin	7440-31-5	0.051	0.02		160	
	noble metal	silver	7440-22-4	0.064	0.02		200	
	non noble metal	lead	7439-92-1	2.430	0.76	0.80	7633	7993
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	6.02	6.03	60232	60310
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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